

PATENT ASSIGNMENT COVER SHEET

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 Stylesheet Version v1.2

EPAS ID: PAT4319438

SUBMISSION TYPE:	NEW ASSIGNMENT	
NATURE OF CONVEYANCE:	ASSIGNMENT	
CONVEYING PARTY DATA		
	Name	Execution Date
	SANYO ELECTRIC CO., LTD.	12/22/2016
RECEIVING PARTY DATA		
Name:	TESSERA ADVANCED TECHNOLOGIES, INC.	
Street Address:	3025 ORCHARD PARKWAY	
City:	SAN JOSE	
State/Country:	CALIFORNIA	
Postal Code:	95134	
PROPERTY NUMBERS Total: 1		
	Property Type	Number
	Patent Number:	8373281
CORRESPONDENCE DATA		
Fax Number:		
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>		
Email:	patentlegal@tessera.com	
Correspondent Name:	TESSERA INTELLECTUAL PROPERTY CORP.	
Address Line 1:	3025 ORCHARD PARKWAY	
Address Line 4:	SAN JOSE, CALIFORNIA 95134	
ATTORNEY DOCKET NUMBER:	ACQ-REC-PANASONIC2	
NAME OF SUBMITTER:	JENNIFER KOSTIC	
SIGNATURE:	/Jennifer Kostic/	
DATE SIGNED:	03/15/2017	
Total Attachments: 6		
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source=2016-12-22_Sanyo to TATI Assignment#page6.tif		

SCHEDULE B-2

**TRANSFER DOCUMENTS
DEED OF ASSIGNMENT**

THIS DEED OF ASSIGNMENT ("Assignment"), EFFECTIVE AS OF December 22, 2016, IS MADE BY AND BETWEEN

Sanyo Electric Co., Ltd., a Japanese corporation with its principal place of business at 1-1, Sanyo-cho, Daito-shi, Osaka 574-8534, Japan (hereinafter "**ASSIGNOR**"); and

Tessera Advanced Technologies, Inc. (hereinafter "**TATI**"), a Delaware corporation having a place of business at 3025 Orchard Parkway, San Jose, California 95134, United States.

WHEREAS:

- A **ASSIGNOR** is the sole owner in respect of the patents and patent applications listed in the attached Appendix (hereinafter "the **PATENTS**"); and
- B **TATI** is desirous of acquiring all of the worldwide right, title and interest in and to the **PATENTS** and the inventions disclosed therein.

NOW, THEREFORE, for good and valuable consideration, receipt of which is hereby acknowledged, **ASSIGNOR** has sold, assigned and transferred, and does hereby sell, assign and transfer to **TATI** all of the worldwide right, title and interest in (i) each of the patents and patent applications set forth in Schedule A, whether or not pending or issued, and all patentable inventions originally disclosed therein to the extent necessary to claim priority before the patent office in the relevant country, and (ii) all reissues, divisionals, continuations, continuations-in-part, reexaminations and foreign counterparts thereof, and all other patents and patent applications that claim priority to patents or patent applications listed in Schedule A (iii), all rights corresponding to any of the foregoing throughout the world (including the right to claim the priority date of any of the **PATENTS** and the right to sue for and recover damages for any past, present or future infringement of the Patents), the same to be held and enjoyed by **TATI** for its own use and enjoyment, and for the use and enjoyment of its successors, assigns and other legal representatives, to the end of the term or terms of said **PATENTS** granted or reissued or reexamined as fully and entirely as the same would have been held and enjoyed by **ASSIGNOR**, if this assignment and sale had not been made.

IN WITNESS WHEREOF, **ASSIGNOR** has caused these presents to be signed by its duly appointed trustee having full authority to convey its property; and **TATI** has caused these presents to be signed by its duly appointed trustee.

And if the issue date and/or patent number of any of the **PATENTS** is unknown to **ASSIGNOR** and **TATI** at the time this Assignment is executed, **ASSIGNOR** does hereby authorize its attorneys to insert on this Assignment the issue date and patent number of said any patent when known.

ASSIGNOR hereby declares that **TATI** may take the steps for recordal of this assignment in the sole name of **TATI**.

ASSIGNOR hereby undertakes that it shall, without further consideration, but at the expense of **TATI**, execute all documents and do all such acts and things as **TATI** may in its absolute discretion consider necessary or desirable to enable Letters Patent or any other form of protection to be issued in respect of any of said **PATENTS** and the patentable inventions originally disclosed therein.

SIGNED for and on behalf of,

ASSIGNOR

by Mihara on Dec. 22, 2016
(Signature) (Date)
Mihara Tashiro, General Manager
(Print Name and Title)

County of Japan)

On this 22nd day of December, 2016 before me, Hironori Morinaga, personally appeared Mihara Tashiro, who proved to me on the basis of satisfactory evidence to be the person whose name is subscribed to the instrument and acknowledged to me that he/she executed the same in his/her authorized capacity and that by his/her signature on the instrument the person, or the entity upon behalf of which the person acted, executed the instrument.

SIGNED for and on behalf of

TATI

by Paul Davis on 12/22/2016
(Signature) (Date)
Paul Davis, SVP and General Counsel
(Print Name and Title)

A notary public or other officer completing this certificate verifies only the identity of the individual who signed the document to which this certificate is attached, and not the truthfulness, accuracy, or validity of that document.

State of California) SS:

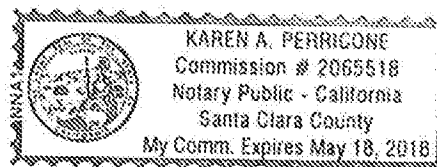
County of Santa Clara

On this 22nd day of December, 2016 before me Karen A. Perricone, Notary Public, personally appeared Paul E. Davis, who proved to me on the basis of satisfactory evidence to be the person whose name is subscribed to the within instrument and acknowledged to me that he/she executed the same in his/her authorized capacity, and that by his/her signature on the instrument the person, or the entity upon behalf of which the person acted, executed the instrument.

I certify under PENALTY OF PERJURY under the laws of the State of California that the foregoing paragraph is true and correct.

WITNESS my hand and official seal.

Karen A. Perricone
(Notary Public)



ATTESTATION OF SIGNATURE PURSUANT TO 28 U.S.C. § 1746

The undersigned witnessed the signature of Minora Tashiro to the above TRANSFER ASSIGNMENT DOCUMENTS on behalf of Sanyo Electric Co., Ltd. and makes the following statements:

1. I am over the age of 18 and competent to testify as to the facts in this Attestation if called upon to do so.

2. Minora Tashiro is personally known to me (or proved to me on the basis of satisfactory evidence) and appeared before me on December 22, 2016 to execute the above Transfer Assignment Document on behalf of Sanyo Electric Co., Ltd..

3. Minora Tashiro executed the above Transfer Assignment Document on behalf of Sanyo Electric Co., Ltd..

I declare under penalty of perjury under the laws of the United States of America that the statements made above in this Attestation are true and correct.

EXECUTED on December 22, 2016

Signature: 森永 護良

Print Name: Hirumi Morinaga

SCHEDULE A

IDENTIFIED PATENTS AND PATENT APPLICATIONS

A-1. United States Listed Issued Patents and Pending Patent Applications

US Issued Patents

Patent Number	Filing Date	Application Number	Issue Date	Publication Number	Title
6,489,685	01/03/2002	10/038,212	12/03/2002	20020135058	Component built-in module and method of manufacturing the same
6,955,948	10/15/2002	10/271,937	10/18/2005	20030062624	Component built-in module and method of manufacturing the same
6,975,516	10/15/2002	10/272,599	12/13/2005	20030090883	Component built-in module and method for producing the same
7,248,482	05/12/2004	10/844,823	07/24/2007	20040226744	Module with built-in circuit component and method for producing the same
7,294,587	05/10/2005	11/126,029	11/13/2007	20050269681	Component built-in module and method for producing the same
8,373,281	07/29/2009	13/056,851	02/12/2013	20110186993	Semiconductor module and portable apparatus provided with semiconductor module

US Pending Applications

None.

A-2. Foreign Listed Issued Patents and Pending Patent Applications

Foreign Issued Patents

Patent Number	Country	Filing Date	Application Number	Issue Date	Publication Number	Title
ZL0210179 9.9	CN	01/18/2002	02101799.9	04/12/2006	1366446 / 1251560	Parts built in module and its making method
ZL2005100 99553.8	CN	01/18/2002	2005100995 53.8	10/24/2007	1767170 /100345279	Component built-in module and method of manufacturing the same
ZL0215633 4.9	CN	10/18/2002	02156334.9	01/03/2007	1418048 / 1293790	Built-in module in element and its making process

Patent Number	Country	Filing Date	Application Number	Issue Date	Publication Number	Title
1304742	DE	10/17/2002	60232572.2 / 02023608.9	06/10/2009	1304742	Manufacture of a module with built-in components
1304742	FR	10/17/2002	02023608.9	06/10/2009	1304742	Method for producing a component built-in module
1304742	GB	10/17/2002	02023608.9	06/10/2009	1304742	Method for producing a component built-in module
10-0507791	KR	01/19/2002	10-2002-0003163	08/03/2005	2002-0062227	Electric component embedded module and method of manufacturing the same
168677	TW	12/27/2001	090132493	11/21/2002	511415	Component built-in module and its manufacturing method
186634	TW	10/14/2002	091123553	09/01/2003	550997	Module with built-in components and the manufacturing method thereof
4272693	JP	10/15/2002	2008-0209266	03/06/2009	2008-294475	Method of manufacturing a component built-in module
5484694	JP	07/31/2008	2008-199072	02/28/2014	2010-040610	Semiconductor module and portable apparatus provided with semiconductor module
5484705	JP	09/30/2008	2008-255795	02/28/2014	2010-087309	Semiconductor module and portable apparatus provided with semiconductor module
3553043	JP	12/26/2001	2001-395071	05/14/2004	2002-290051	Component built-in module and method of manufacturing the same
4509645	JP	05/14/2004	2004-145374	05/14/2010	2005-005692	Module with built-in circuit component and method for producing the same

Foreign Pending Applications

None.

A-3. US and Foreign Listed Abandoned/Expired Patents and Applications

Patent Number	Country	Filing Date	Application Number	Issue Date	Publication Number	Title
ZL200410044718.7	CN	05/17/2004	200410044718.7	06/10/2009	1551719 / 100499969	Module with built-in circuit component and method for producing the same

Patent Number	Country	Filing Date	Application Number	Issue Date	Publication Number	Title
	EP	10/17/2002	09152986.7		2056349	Component built-in module and method for producing the same
	EP	01/09/2002	02000534.4		1225629	Component built-in module and method of manufacturing the same
1304742	EP	10/17/2002	02023608.9	06/10/2009	1304742	Method for producing a component built-in module
	JP	10/18/2001	2001-320704			Component built-in module and method for producing the same
	JP	01/19/2001	2001-011656			Component built-in module and method of manufacturing the same
	JP	10/15/2002	2002-301043		2003-197849	Component built-in module and method for producing the same
	JP	05/16/2003	2003-139345			Module with built-in circuit component and method for producing the same
	KR	10/18/2002	2002-0063874		2003-0032892	Component embedded module and manufacturing method thereof
	WO	07/29/2009	PCT/JP2009/003598		2010013470	Semiconductor module and portable apparatus provided with semiconductor module